



Welcome to [E-XFL.COM](https://www.e-xfl.com)

What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Not For New Designs
Core Processor	R8C
Core Size	16-Bit
Speed	20MHz
Connectivity	CANbus, I ² C, IEBus, LINbus, SIO, SSU, UART/USART
Peripherals	POR, PWM, Voltage Detect, WDT
Number of I/O	43
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	4K x 8
RAM Size	2.5K x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	A/D 12x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	48-LQFP
Supplier Device Package	48-LQFP (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f21346wjfp-u0

Table 1.3 Specifications for R8C/34X Group (1)

Item	Function	Specification
CPU	Central processing unit	R8C CPU core <ul style="list-style-type: none"> • Number of fundamental instructions: 89 • Minimum instruction execution time: 50 ns ($f(XIN) = 20$ MHz, $VCC = 2.7$ to 5.5 V) • Multiplier: 16 bits \times 16 bits \rightarrow 32 bits • Multiply-accumulate instruction: 16 bits \times 16 bits + 32 bits \rightarrow 32 bits • Operating mode: Single-chip mode (address space: 1 Mbyte)
Memory	ROM, RAM, Data flash	Refer to Table 1.10 Product List for R8C/34X Group .
Power Supply Voltage Detection	Voltage detection circuit	<ul style="list-style-type: none"> • Power-on reset • Voltage detection 3 (detection level of voltage detection 1 selectable)
I/O Ports	Programmable I/O ports	<ul style="list-style-type: none"> • Input-only: 1 pin • CMOS I/O ports: 43, selectable pull-up resistor
Clock	Clock generation circuits	<p>3 circuits: XIN clock oscillation circuit (with on-chip feedback resistor), High-speed on-chip oscillator (with frequency adjustment function), Low-speed on-chip oscillator</p> <ul style="list-style-type: none"> • Oscillation stop detection: XIN clock oscillation stop detection function • Frequency divider circuit: Dividing selectable 1, 2, 4, 8, and 16 • Low power consumption modes: Standard operating mode (high-speed clock, high-speed on-chip oscillator, low-speed on-chip oscillator), wait mode, stop mode
Interrupts		<ul style="list-style-type: none"> • Interrupt vectors: 69 • External: 9 sources (INT \times 5, key input \times 4) • Priority levels: 7 levels
Watchdog Timer		<ul style="list-style-type: none"> • 14 bits \times 1 (with prescaler) • Reset start selectable • Low-speed on-chip oscillator for watchdog timer selectable
DTC (Data Transfer Controller)		<ul style="list-style-type: none"> • 1 channel • Activation sources: 31 • Transfer modes: 2 (normal mode, repeat mode)
Timer	Timer RA	8 bits (with 8-bit prescaler) \times 1 Timer mode (period timer), pulse output mode (output level inverted every period), event counter mode, pulse width measurement mode, pulse period measurement mode
	Timer RB	8 bits (with 8-bit prescaler) \times 1 Timer mode (period timer), programmable waveform generation mode (PWM output), programmable one-shot generation mode, programmable wait one-shot generation mode
	Timer RC	16 bits (with 4 capture/compare registers) \times 1 Timer mode (input capture function, output compare function), PWM mode (output 3 pins), PWM2 mode (PWM output pin)
	Timer RD	16 bits (with 4 capture/compare registers) \times 2 Timer mode (input capture function, output compare function), PWM mode (output 6 pins), reset synchronous PWM mode (output three-phase waveforms (6 pins), sawtooth wave modulation), complementary PWM mode (output three-phase waveforms (6 pins), triangular wave modulation), PWM3 mode (PWM output 2 pins with fixed period)
	Timer RE	8 bits \times 1 Output compare mode

Table 1.4 Specifications for R8C/34X Group (2)

Item	Function	Specification
Serial Interface	UART0	1 channel Clock synchronous serial I/O, UART
	UART2	1 channel Clock synchronous serial I/O, UART, I ² C mode (I ² C-bus), IE mode (IEBus), multiprocessor communication function
Synchronous Serial Communication Unit (SSU)		1 channel
LIN Module		Hardware LIN: 1 (timer RA, UART0)
CAN Module		1 channel, 16 Mailboxes (conforms to the ISO 11898-1)
A/D Converter		10-bit resolution × 12 channels, includes sample and hold function, with sweep mode
Flash Memory		<ul style="list-style-type: none"> • Programming and erasure voltage: VCC = 2.7 to 5.5 V • Programming and erasure endurance: 100 times (program ROM) • Program security: ROM code protect, ID code check • Debug functions: On-chip debug, on-board flash rewrite function
Operating Frequency/Supply Voltage		f(XIN) = 20 MHz (VCC = 2.7 to 5.5 V)
Current Consumption		Typ. 7 mA (VCC = 5.0 V, f(XIN) = 20 MHz)
Operating Ambient Temperature		-40 to 85°C (J version) -40 to 125°C (K version) ⁽¹⁾
Package		48-pin LQFP Package code: PLQP0048KB-A (previous code: 48P6Q-A)

Note:

1. Specify the K version if K version functions are to be used.

Table 1.10 Product List for R8C/34X Group **Current of Jan 2013**

Part No.	ROM Capacity	RAM Capacity	Package Type	Remarks
	Program ROM			
R5F21346XJFP	32 Kbytes	2.5 Kbytes	PLQP0048KB-A	J version
R5F21347XJFP	48 Kbytes	4 Kbytes	PLQP0048KB-A	
R5F21348XJFP	64 Kbytes	6 Kbytes	PLQP0048KB-A	
R5F2134AXJFP	96 Kbytes	8 Kbytes	PLQP0048KB-A	
R5F2134CXJFP	128 Kbytes	10 Kbytes	PLQP0048KB-A	
R5F21346XKFP	32 Kbytes	2.5 Kbytes	PLQP0048KB-A	K version
R5F21347XKFP	48 Kbytes	4 Kbytes	PLQP0048KB-A	
R5F21348XKFP	64 Kbytes	6 Kbytes	PLQP0048KB-A	
R5F2134AXKFP	96 Kbytes	8 Kbytes	PLQP0048KB-A	
R5F2134CXKFP	128 Kbytes	10 Kbytes	PLQP0048KB-A	

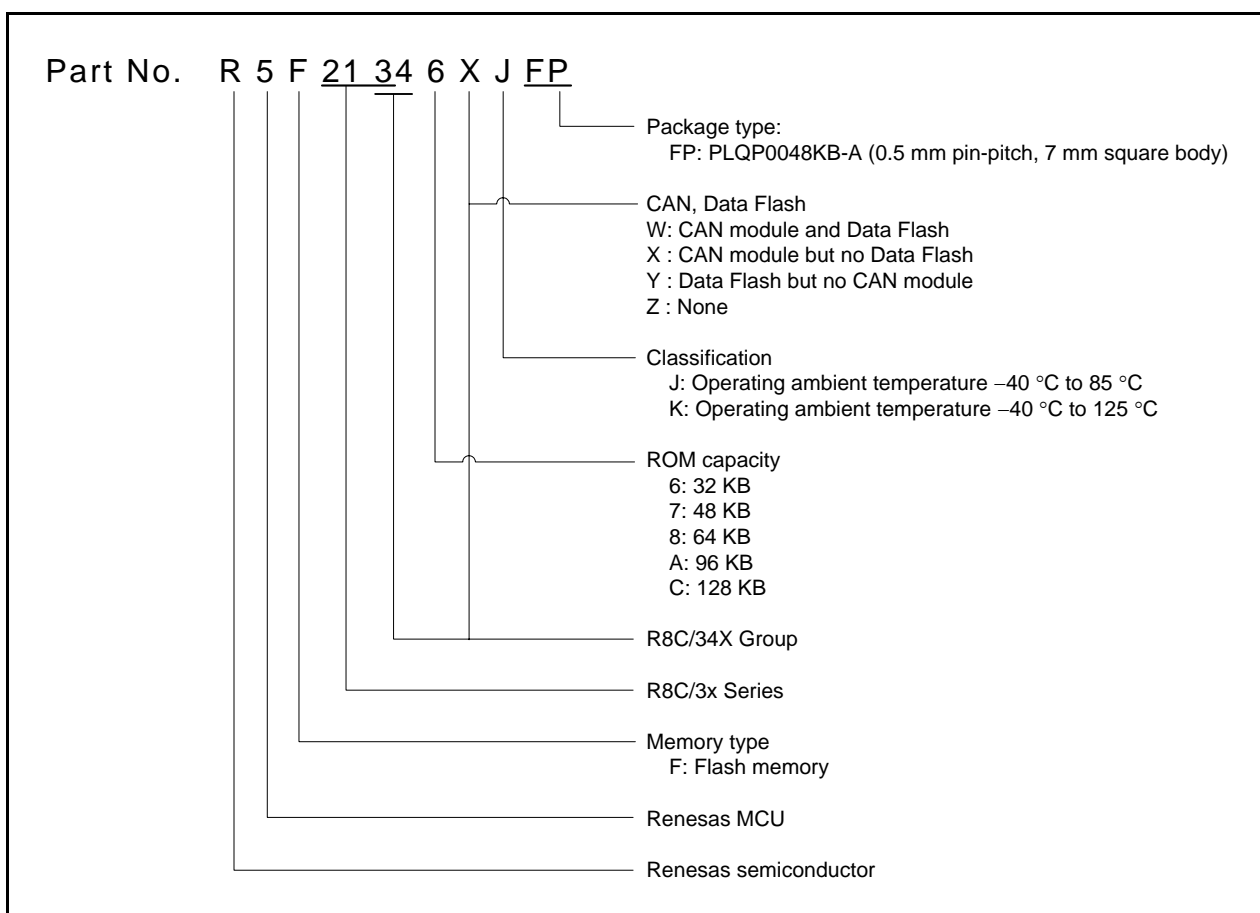


Figure 1.2 Part Number, Memory Size, and Package of R8C/34X Group

Table 1.11 Product List for R8C/34Y Group **Current of Jan 2013**

Part No.	ROM Capacity		RAM Capacity	Package Type	Remarks
	Program ROM	Data flash			
R5F21346YJFP	32 Kbytes	1 Kbyte × 4	2.5 Kbytes	PLQP0048KB-A	J version
R5F21347YJFP	48 Kbytes	1 Kbyte × 4	4 Kbytes	PLQP0048KB-A	
R5F21348YJFP	64 Kbytes	1 Kbyte × 4	6 Kbytes	PLQP0048KB-A	
R5F2134AYJFP	96 Kbytes	1 Kbyte × 4	8 Kbytes	PLQP0048KB-A	
R5F2134CYJFP	128 Kbytes	1 Kbyte × 4	10 Kbytes	PLQP0048KB-A	
R5F21346YKFP	32 Kbytes	1 Kbyte × 4	2.5 Kbytes	PLQP0048KB-A	K version
R5F21347YKFP	48 Kbytes	1 Kbyte × 4	4 Kbytes	PLQP0048KB-A	
R5F21348YKFP	64 Kbytes	1 Kbyte × 4	6 Kbytes	PLQP0048KB-A	
R5F2134AYKFP	96 Kbytes	1 Kbyte × 4	8 Kbytes	PLQP0048KB-A	
R5F2134CYKFP	128 Kbytes	1 Kbyte × 4	10 Kbytes	PLQP0048KB-A	

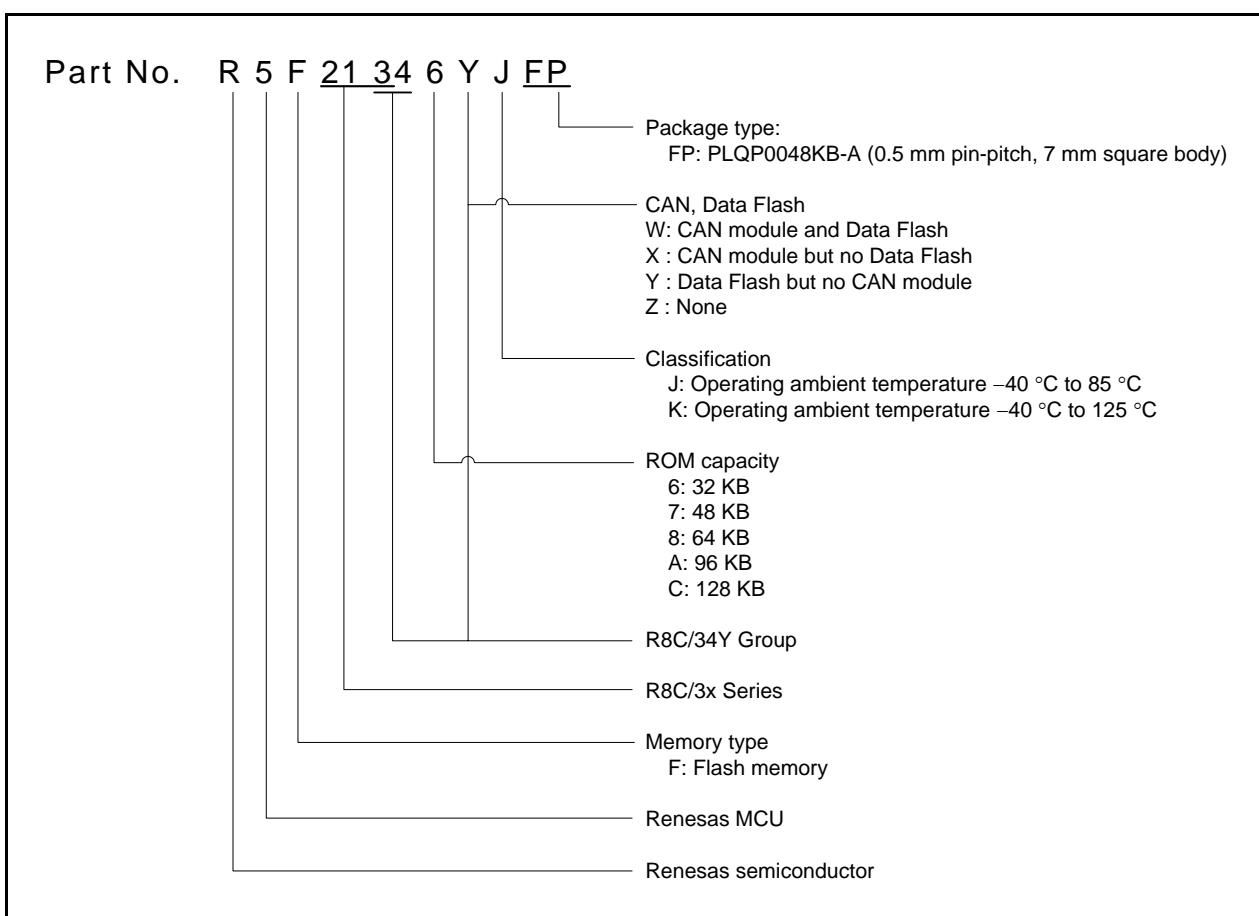


Figure 1.3 Part Number, Memory Size, and Package of R8C/34Y Group

1.3 Block Diagram

Figure 1.5 shows a Block Diagram.

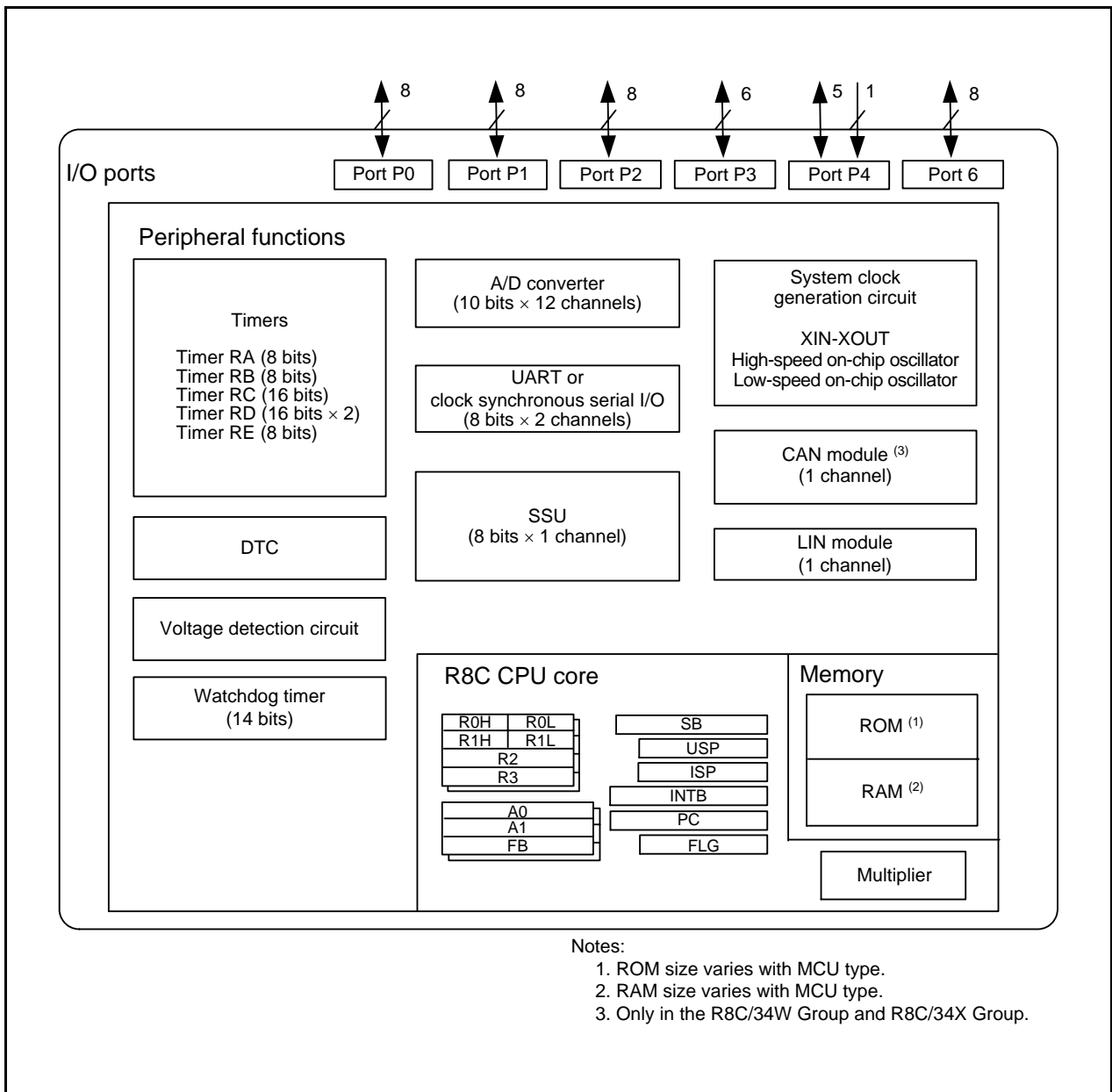


Figure 1.5 Block Diagram

3. Memory

3.1 R8C/34W Group

Figure 3.1 is a Memory Map of R8C/34W Group. The R8C/34W Group has a 1-Mbyte address space from addresses 00000h to FFFFFh. The internal ROM (program ROM) is allocated lower addresses, beginning with address 0FFFFh. For example, a 48-Kbyte internal ROM area is allocated addresses 04000h to 0FFFFh. The fixed interrupt vector table is allocated addresses 0FFDCh to 0FFFFh. The starting address of each interrupt routine is stored here.

The internal ROM (data flash) is allocated addresses 03000h to 03FFFh.

The internal RAM is allocated higher addresses, beginning with address 00400h. For example, a 4-Kbyte internal RAM area is allocated addresses 00400h to 013FFh. The internal RAM is used not only for data storage but also as a stack area when a subroutine is called or when an interrupt request is acknowledged.

Special function registers (SFRs) are allocated addresses 00000h to 002FFh and 02C00h to 02FFFh (the SFR areas for the CAN, DTC, and other modules). Peripheral function control registers are allocated here. All unallocated spaces within the SFRs are reserved and cannot be accessed by users.

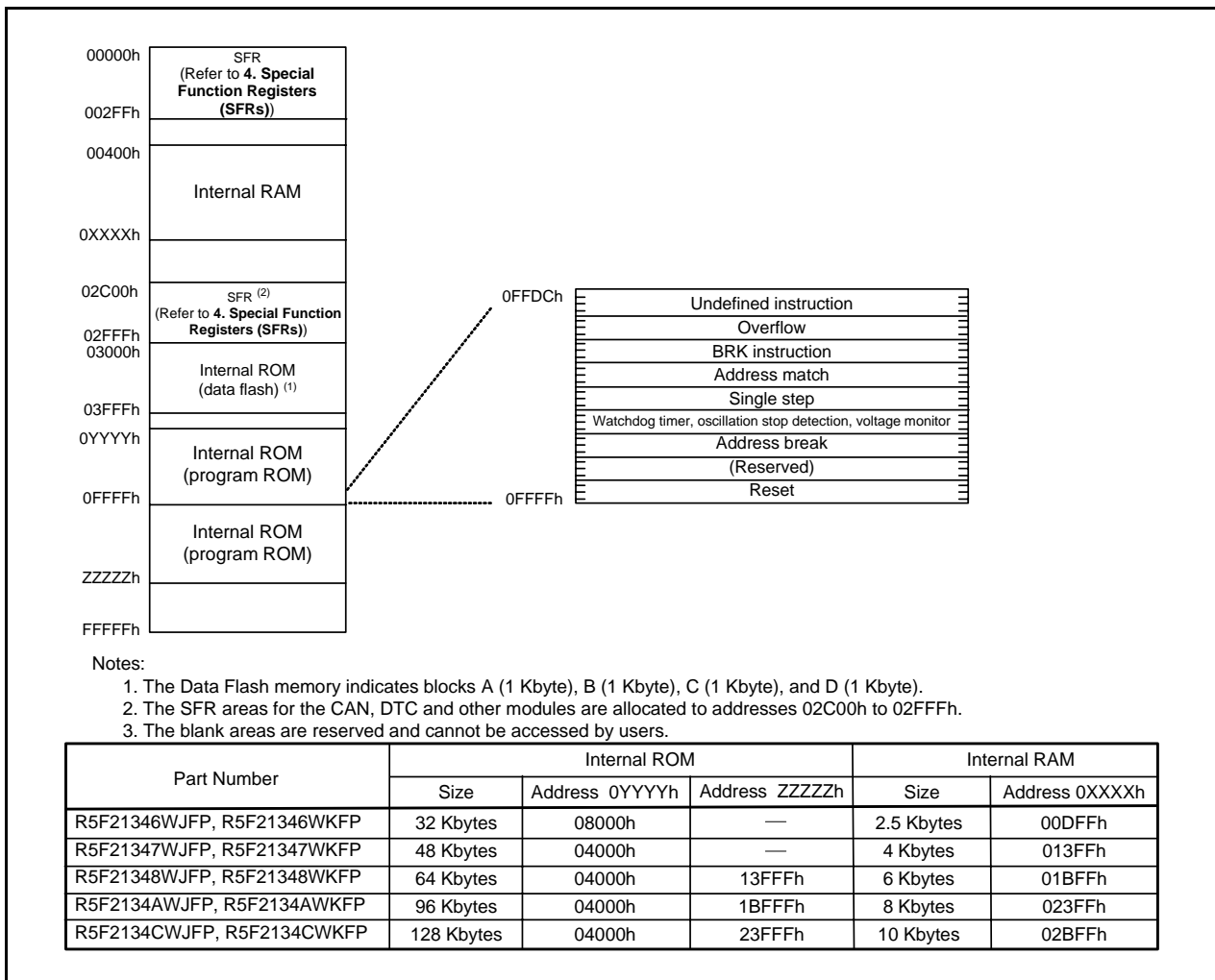


Figure 3.1 Memory Map of R8C/34W Group

3.4 R8C/34Z Group

Figure 3.4 is a Memory Map of R8C/34Z Group. The R8C/34Z Group has a 1-Mbyte address space from addresses 00000h to FFFFFh. The internal ROM (program ROM) is allocated lower addresses, beginning with address 0FFFFh. For example, a 48-Kbyte internal ROM area is allocated addresses 04000h to 0FFFFh.

The fixed interrupt vector table is allocated addresses 0FFDCh to 0FFFFh. The starting address of each interrupt routine is stored here.

The internal RAM is allocated higher addresses, beginning with address 00400h. For example, a 4-Kbyte internal RAM area is allocated addresses 00400h to 013FFh. The internal RAM is used not only for data storage but also as a stack area when a subroutine is called or when an interrupt request is acknowledged.

Special function registers (SFRs) are allocated addresses 00000h to 002FFh and 02C00h to 02FFFh (the SFR areas for the DTC and other modules). Peripheral function control registers are allocated here. All unallocated spaces within the SFRs are reserved and cannot be accessed by users.

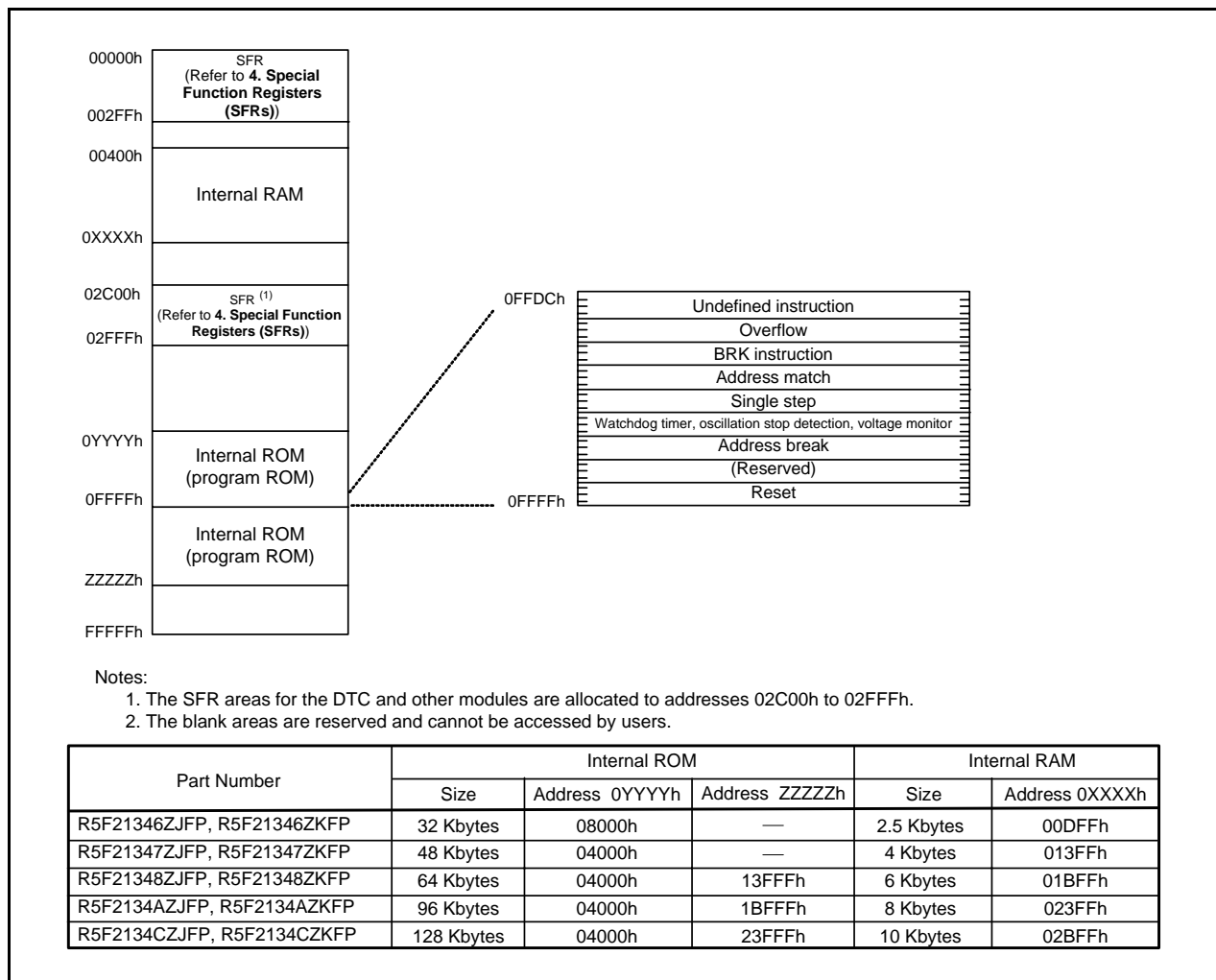


Figure 3.4 Memory Map of R8C/34Z Group

Table 4.4 SFR Information (4) (1)

Address	Register	Symbol	After reset
00C0h	A/D Register 0	AD0	XXh 000000XXb
00C1h	A/D Register 1	AD1	XXh
00C2h			000000XXb
00C3h	A/D Register 2	AD2	XXh
00C4h			000000XXb
00C5h	A/D Register 3	AD3	XXh
00C6h			000000XXb
00C7h	A/D Register 4	AD4	XXh
00C8h			000000XXb
00C9h	A/D Register 5	AD5	XXh
00CAh			000000XXb
00CBh	A/D Register 6	AD6	XXh
00CCh			000000XXb
00CDh	A/D Register 7	AD7	XXh
00CEh			000000XXb
00CFh			
00D0h			
00D1h			
00D2h			
00D3h			
00D4h	A/D Mode Register	ADMOD	00h
00D5h	A/D Input Select Register	ADINSEL	1100000b
00D6h	A/D Control Register 0	ADCON0	00h
00D7h	A/D Control Register 1	ADCON1	00h
00D8h			
00D9h			
00DAh			
00DBh			
00DCh			
00DDh			
00DEh			
00DFh			
00E0h	Port P0 Register	P0	XXh
00E1h	Port P1 Register	P1	XXh
00E2h	Port P0 Direction Register	PD0	00h
00E3h	Port P1 Direction Register	PD1	00h
00E4h	Port P2 Register	P2	XXh
00E5h	Port P3 Register	P3	XXh
00E6h	Port P2 Direction Register	PD2	00h
00E7h	Port P3 Direction Register	PD3	00h
00E8h	Port P4 Register	P4	XXh
00E9h			
00EAh	Port P4 Direction Register	PD4	00h
00EBh			
00ECh	Port P6 Register	P6	XXh
00EDh			
00EEh	Port P6 Direction Register	PD6	00h
00EFh			
00F0h			
00F1h			
00F2h			
00F3h			
00F4h			
00F5h			
00F6h			
00F7h			
00F8h			
00F9h			
00FAh			
00FBh			
00FCh			
00FDh			
00FEh			
00FFh			

X: Undefined

Note:

1. The blank areas are reserved and cannot be accessed by users.

Table 4.6 SFR Information (6) (1)

Address	Register	Symbol	After reset
0140h	Timer RD Control Register 0	TRDCR0	00h
0141h	Timer RD I/O Control Register A0	TRDIORA0	10001000b
0142h	Timer RD I/O Control Register C0	TRDIORC0	10001000b
0143h	Timer RD Status Register 0	TRDSR0	11100000b
0144h	Timer RD Interrupt Enable Register 0	TRDIER0	11100000b
0145h	Timer RD PWM Mode Output Level Control Register 0	TRDPOCR0	11111000b
0146h	Timer RD Counter 0	TRD0	00h
0147h			00h
0148h	Timer RD General Register A0	TRDGRA0	FFh
0149h			FFh
014Ah	Timer RD General Register B0	TRDGRB0	FFh
014Bh			FFh
014Ch	Timer RD General Register C0	TRDGRC0	FFh
014Dh			FFh
014Eh	Timer RD General Register D0	TRDGRD0	FFh
014Fh			FFh
0150h	Timer RD Control Register 1	TRDCR1	00h
0151h	Timer RD I/O Control Register A1	TRDIORA1	10001000b
0152h	Timer RD I/O Control Register C1	TRDIORC1	10001000b
0153h	Timer RD Status Register 1	TRDSR1	11000000b
0154h	Timer RD Interrupt Enable Register 1	TRDIER1	11100000b
0155h	Timer RD PWM Mode Output Level Control Register 1	TRDPOCR1	11111000b
0156h	Timer RD Counter 1	TRD1	00h
0157h			00h
0158h	Timer RD General Register A1	TRDGRA1	FFh
0159h			FFh
015Ah	Timer RD General Register B1	TRDGRB1	FFh
015Bh			FFh
015Ch	Timer RD General Register C1	TRDGRC1	FFh
015Dh			FFh
015Eh	Timer RD General Register D1	TRDGRD1	FFh
015Fh			FFh
0160h			
0161h			
0162h			
0163h			
0164h			
0165h			
0166h			
0167h			
0168h			
0169h			
016Ah			
016Bh			
016Ch			
016Dh			
016Eh			
016Fh			
0170h			
0171h			
0172h			
0173h			
0174h			
0175h			
0176h			
0177h			
0178h			
0179h			
017Ah			
017Bh			
017Ch			
017Dh			
017Eh			
017Fh			

X: Undefined

Note:

1. The blank areas are reserved and cannot be accessed by users.

Table 4.9 SFR Information (9) (1)

Address	Register	Symbol	After reset
2C00h	DTC Transfer Vector Area		XXh
2C01h	DTC Transfer Vector Area		XXh
2C02h	DTC Transfer Vector Area		XXh
2C03h	DTC Transfer Vector Area		XXh
2C04h	DTC Transfer Vector Area		XXh
2C05h			
2C06h			
2C07h			
2C08h	DTC Transfer Vector Area		XXh
2C09h	DTC Transfer Vector Area		XXh
2C0Ah	DTC Transfer Vector Area		XXh
:	DTC Transfer Vector Area		XXh
:	DTC Transfer Vector Area		XXh
2C3Ah			
2C3Bh			
2C3Ch			
2C3Dh			
2C3Eh			
2C3Fh			
2C40h	DTC Control Data 0	DTCD0	XXh
2C41h			XXh
2C42h			XXh
2C43h			XXh
2C44h			XXh
2C45h			XXh
2C46h			XXh
2C47h			XXh
2C48h	DTC Control Data 1	DTCD1	XXh
2C49h			XXh
2C4Ah			XXh
2C4Bh			XXh
2C4Ch			XXh
2C4Dh			XXh
2C4Eh			XXh
2C4Fh			XXh
2C50h	DTC Control Data 2	DTCD2	XXh
2C51h			XXh
2C52h			XXh
2C53h			XXh
2C54h			XXh
2C55h			XXh
2C56h			XXh
2C57h			XXh
2C58h	DTC Control Data 3	DTCD3	XXh
2C59h			XXh
2C5Ah			XXh
2C5Bh			XXh
2C5Ch			XXh
2C5Dh			XXh
2C5Eh			XXh
2C5Fh			XXh
2C60h	DTC Control Data 4	DTCD4	XXh
2C61h			XXh
2C62h			XXh
2C63h			XXh
2C64h			XXh
2C65h			XXh
2C66h			XXh
2C67h			XXh
2C68h	DTC Control Data 5	DTCD5	XXh
2C69h			XXh
2C6Ah			XXh
2C6Bh			XXh
2C6Ch			XXh
2C6Dh			XXh
2C6Eh			XXh
2C6Fh			XXh

X: Undefined

Note:

1. The blank areas are reserved and cannot be accessed by users.

Table 4.10 SFR Information (10) (1)

Address	Register	Symbol	After reset
2C70h	DTC Control Data 6	DTCD6	XXh
2C71h			XXh
2C72h			XXh
2C73h			XXh
2C74h			XXh
2C75h			XXh
2C76h			XXh
2C77h			XXh
2C78h	DTC Control Data 7	DTCD7	XXh
2C79h			XXh
2C7Ah			XXh
2C7Bh			XXh
2C7Ch			XXh
2C7Dh			XXh
2C7Eh			XXh
2C7Fh			XXh
2C80h	DTC Control Data 8	DTCD8	XXh
2C81h			XXh
2C82h			XXh
2C83h			XXh
2C84h			XXh
2C85h			XXh
2C86h			XXh
2C87h			XXh
2C88h	DTC Control Data 9	DTCD9	XXh
2C89h			XXh
2C8Ah			XXh
2C8Bh			XXh
2C8Ch			XXh
2C8Dh			XXh
2C8Eh			XXh
2C8Fh			XXh
2C90h	DTC Control Data 10	DTCD10	XXh
2C91h			XXh
2C92h			XXh
2C93h			XXh
2C94h			XXh
2C95h			XXh
2C96h			XXh
2C97h			XXh
2C98h	DTC Control Data 11	DTCD11	XXh
2C99h			XXh
2C9Ah			XXh
2C9Bh			XXh
2C9Ch			XXh
2C9Dh			XXh
2C9Eh			XXh
2C9Fh			XXh
2CA0h	DTC Control Data 12	DTCD12	XXh
2CA1h			XXh
2CA2h			XXh
2CA3h			XXh
2CA4h			XXh
2CA5h			XXh
2CA6h			XXh
2CA7h			XXh
2CA8h	DTC Control Data 13	DTCD13	XXh
2CA9h			XXh
2CAAh			XXh
2CABh			XXh
2CACH			XXh
2CADh			XXh
2CAEh			XXh
2CAFh			XXh

X: Undefined

Note:

1. The blank areas are reserved and cannot be accessed by users.

Table 4.15 SFR Information (15) (1)

Address	Register	Symbol	After reset
2EB0h	CAN0 Mailbox11 : Message ID	C0MB11	XXh
2EB1h			XXh
2EB2h			XXh
2EB3h			XXh
2EB4h			
2EB5h	CAN0 Mailbox11 : Data length		XXh
2EB6h	CAN0 Mailbox11 : Data field		XXh
2EB7h		XXh	
2EB8h		XXh	
2EB9h		XXh	
2EBAh		XXh	
2EBBh		XXh	
2EBCh		XXh	
2EBDh		XXh	
2EBEh		CAN0 Mailbox11 : Time stamp	
2EBFh			XXh
2EC0h	CAN0 Mailbox12 : Message ID	C0MB12	XXh
2EC1h			XXh
2EC2h			XXh
2EC3h			XXh
2EC4h			
2EC5h	CAN0 Mailbox12 : Data length		XXh
2EC6h	CAN0 Mailbox12 : Data field		XXh
2EC7h		XXh	
2EC8h		XXh	
2EC9h		XXh	
2ECAh		XXh	
2ECBh		XXh	
2ECCh		XXh	
2ECDh		XXh	
2ECEh		CAN0 Mailbox12 : Time stamp	
2ECFh			XXh
2ED0h	CAN0 Mailbox13 : Message ID	C0MB13	XXh
2ED1h			XXh
2ED2h			XXh
2ED3h			XXh
2ED4h			
2ED5h	CAN0 Mailbox13 : Data length		XXh
2ED6h	CAN0 Mailbox13 : Data field		XXh
2ED7h		XXh	
2ED8h		XXh	
2ED9h		XXh	
2EDAh		XXh	
2EDBh		XXh	
2EDCh		XXh	
2EDDh		XXh	
2EDEh		CAN0 Mailbox13 : Time stamp	
2EDFh			XXh
2EE0h	CAN0 Mailbox14 : Message ID	C0MB14	XXh
2EE1h			XXh
2EE2h			XXh
2EE3h			XXh
2EE4h			
2EE5h	CAN0 Mailbox14 : Data length		XXh
2EE6h	CAN0 Mailbox14 : Data field		XXh
2EE7h		XXh	
2EE8h		XXh	
2EE9h		XXh	
2EEAh		XXh	
2EEBh		XXh	
2EECh		XXh	
2EEDh		XXh	
2EEEh		CAN0 Mailbox14 : Time stamp	
2EEFh			XXh

X: Undefined

Note:

- The blank areas are reserved and cannot be accessed by users.

5. Electrical Characteristics

Table 5.1 Absolute Maximum Ratings

Symbol	Parameter	Condition	Rated Value	Unit
V _{CC} /AV _{CC}	Supply voltage		-0.3 to 6.5	V
V _I	Input voltage (1)		-0.3 to V _{CC} + 0.3	V
I _{IN}	Input current (1)	(2, 3, 4)	-4 to 4	mA
V _O	Output voltage		-0.3 to V _{CC} + 0.3	V
P _d	Power dissipation	-40 °C ≤ T _{opr} < 85 °C	300	mW
		85 °C ≤ T _{opr} < 125 °C	125	mW
T _{opr}	Operating ambient temperature		-40 to 85 (J version) / -40 to 125 (K version)	°C
T _{stg}	Storage temperature		-65 to 150	°C

Notes:

1. Meet the specified range for the input voltage or the input current.
2. Applicable ports: P0 to P2, P3_0, P3_1, P3_3 to P3_5, P3_7, P4_3 to P4_5, P6
3. The total input current must be 12 mA or less.
4. Even if no voltage is supplied to V_{CC}, the input current may cause the MCU to be powered on and operate. When a voltage is supplied to V_{CC}, the input current may cause the supply voltage to rise. Since operations in any cases other than above are not guaranteed, use the power supply circuit in the system to ensure the supply voltage for the MCU is stable within the specified range.

Table 5.14 Timing Requirements of SSU (1)

Symbol	Parameter		Conditions	Standard			Unit
				Min.	Typ.	Max.	
tsucyc	SSCK clock cycle time			4	–	–	tcyc (2)
tHI	SSCK clock "H" width			0.4	–	0.6	tsucyc
tLO	SSCK clock "L" width			0.4	–	0.6	tsucyc
tRISE	SSCK clock rising time	Master		–	–	1	tcyc (2)
		Slave		–	–	1	μs
tFALL	SSCK clock falling time	Master		–	–	1	tcyc (2)
		Slave		–	–	1	μs
tsu	SSO, SSI data input setup time			100	–	–	ns
tH	SSO, SSI data input hold time			1	–	–	tcyc (2)
tLEAD	$\overline{\text{SCS}}$ setup time	Slave		1tcyc + 50	–	–	ns
tLAG	$\overline{\text{SCS}}$ hold time	Slave		1tcyc + 50	–	–	ns
tOD	SSO, SSI data output delay time			–	–	1	tcyc (2)
tSA	SSI slave access time		$2.7 \text{ V} \leq V_{\text{CC}} \leq 5.5 \text{ V}$	–	–	1.5tcyc + 100	ns
tOR	SSI slave out open time		$2.7 \text{ V} \leq V_{\text{CC}} \leq 5.5 \text{ V}$	–	–	1.5tcyc + 100	ns

Notes:

1. The measurement condition is $V_{\text{CC}} = 2.7$ to 5.5 V and $T_{\text{opr}} = -40$ to 85°C (J version) / -40 to 125°C (K version).
2. $1\text{tcyc} = 1/f_1(\text{s})$

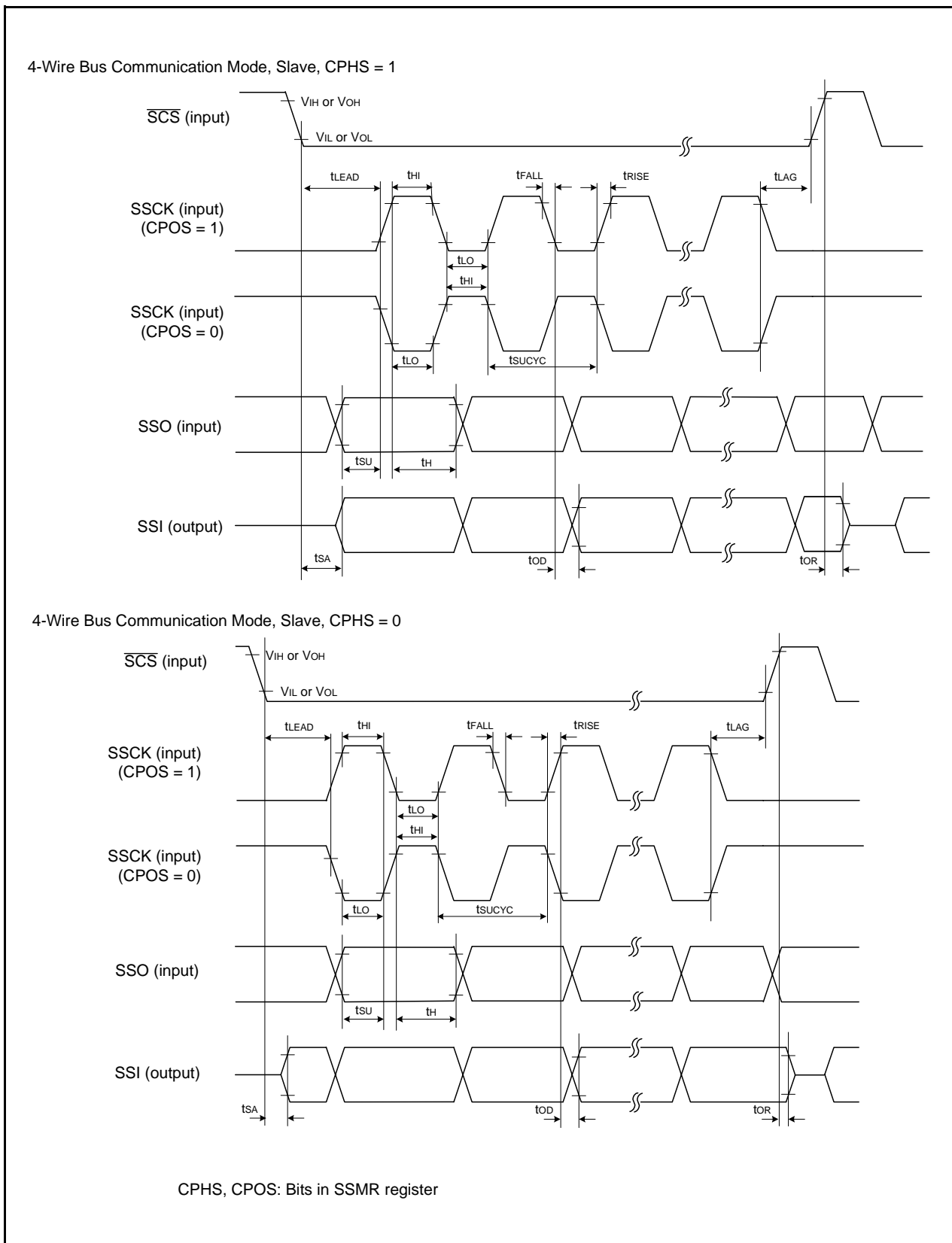


Figure 5.5 I/O Timing of SSU (Slave)

Table 5.16 Electrical Characteristics (2) [3.3 V ≤ V_{CC} ≤ 5.5 V]
(T_{opr} = -40 to 85°C (J version), unless otherwise specified.)

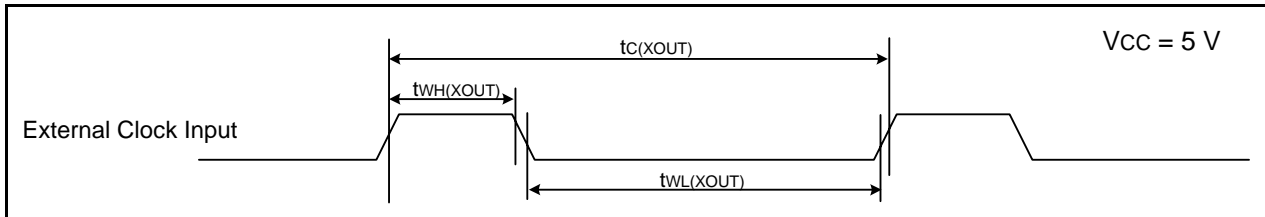
Symbol	Parameter	Condition	Standard			Unit	
			Min.	Typ.	Max.		
I _{CC}	Power supply current (V _{CC} = 3.3 to 5.5 V) Single-chip mode, output pins are open, other pins are V _{SS}	High-speed clock mode (1)	XIN = 20 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz No division	–	7.0	15	mA
			XIN = 16 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz No division	–	5.6	12.5	mA
			XIN = 10 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz No division	–	3.6	–	mA
			XIN = 20 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8	–	3.0	–	mA
			XIN = 16 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8	–	2.2	–	mA
			XIN = 10 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8	–	1.5	–	mA
		High-speed on-chip oscillator mode (1)	XIN clock off High-speed on-chip oscillator on f _{OCO-F} = 20 MHz Low-speed on-chip oscillator on = 125 kHz No division	–	7.0	15	mA
			XIN clock off High-speed on-chip oscillator on f _{OCO-F} = 20 MHz Low-speed on-chip oscillator on = 125 kHz Divide-by-8	–	3.0	–	mA
		Low-speed on-chip oscillator mode	XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8, FMR27 = 1, VCA20 = 0	–	90	180	μA
		Wait mode	XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz While a WAIT instruction is executed Peripheral clock operation VCA27 = VCA26 = VCA25 = 0 VCA20 = 1	–	15	110	μA
			XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz While a WAIT instruction is executed Peripheral clock off VCA27 = VCA26 = VCA25 = 0 VCA20 = 1	–	5	100	μA
		Stop mode	XIN clock off, T _{opr} = 25°C High-speed on-chip oscillator off Low-speed on-chip oscillator off CM10 = 1 Peripheral clock off VCA27 = VCA26 = VCA25 = 0	–	2.0	5.0	μA
			XIN clock off, T _{opr} = 85°C High-speed on-chip oscillator off Low-speed on-chip oscillator off CM10 = 1 Peripheral clock off VCA27 = VCA26 = VCA25 = 0	–	15.0	–	μA

Note:

- The typical value (Typ.) indicates the current value when the CPU and the memory operate. The maximum value (Max.) indicates the current when the CPU, the memory, and the peripheral functions operate and the flash memory is programmed/erased.

Timing Requirements**(Unless Otherwise Specified: $V_{CC} = 5\text{ V}$, $V_{SS} = 0\text{ V}$ at $T_{opr} = -40^{\circ}\text{C}$ to 85°C (J ver)/ -40°C to 125°C (K ver))****Table 5.18 External clock input (XOUT)**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(XOUT)}$	XOUT input cycle time	50	–	ns
$t_{WH(XOUT)}$	XOUT input "H" width	24	–	ns
$t_{WL(XOUT)}$	XOUT input "L" width	24	–	ns

**Figure 5.7 External Clock Input Timing Diagram when $V_{CC} = 5\text{ V}$** **Table 5.19 TRAI0 Input**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TRAIO)}$	TRAIO input cycle time	100	–	ns
$t_{WH(TRAIO)}$	TRAIO input "H" width	40	–	ns
$t_{WL(TRAIO)}$	TRAIO input "L" width	40	–	ns

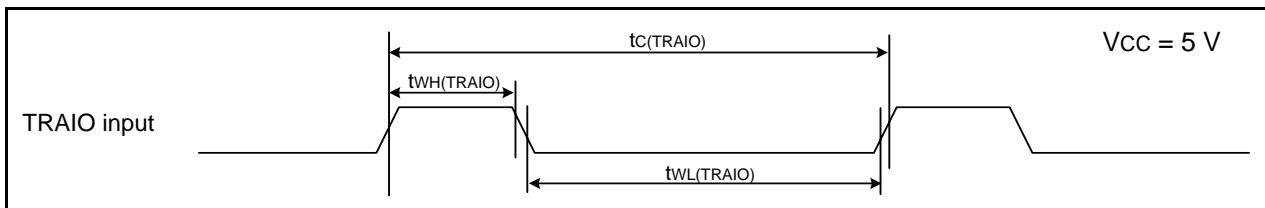
**Figure 5.8 TRAI0 Input Timing Diagram when $V_{CC} = 5\text{ V}$**

Table 5.24 Electrical Characteristics (4) [2.7 V ≤ V_{CC} < 3.3 V]
(T_{opr} = -40 to 125°C (K version), unless otherwise specified.)

Symbol	Parameter	Condition	Standard			Unit	
			Min.	Typ.	Max.		
I _{CC}	Power supply current (V _{CC} = 2.7 to 3.3 V) Single-chip mode, output pins are open, other pins are V _{SS}	High-speed clock mode (1)	XIN = 20 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz No division	–	7.0	14.5	mA
			XIN = 16 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz No division	–	5.6	12.0	mA
			XIN = 10 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz No division	–	3.6	–	mA
			XIN = 20 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8	–	3.0	–	mA
			XIN = 16 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8	–	2.2	–	mA
			XIN = 10 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8	–	1.5	–	mA
			XIN clock off High-speed on-chip oscillator on fOCO-F = 20 MHz Low-speed on-chip oscillator on = 125 kHz No division	–	7.0	14.5	mA
		High-speed on-chip oscillator mode (1)	XIN clock off High-speed on-chip oscillator on fOCO-F = 20 MHz Low-speed on-chip oscillator on = 125 kHz Divide-by-8	–	3.0	–	mA
			Low-speed on-chip oscillator mode	XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8, FMR27 = 1, VCA20 = 0	–	85	390
		Wait mode	XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz While a WAIT instruction is executed Peripheral clock operation VCA27 = VCA26 = VCA25 = 0 VCA20 = 1	–	15	320	μA
			XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz While a WAIT instruction is executed Peripheral clock off VCA27 = VCA26 = VCA25 = 0 VCA20 = 1	–	5	310	μA
		Stop mode	XIN clock off, T _{opr} = 25°C High-speed on-chip oscillator off Low-speed on-chip oscillator off CM10 = 1 Peripheral clock off VCA27 = VCA26 = VCA25 = 0	–	2.0	5.0	μA
			XIN clock off, T _{opr} = 125°C High-speed on-chip oscillator off Low-speed on-chip oscillator off CM10 = 1 Peripheral clock off VCA27 = VCA26 = VCA25 = 0	–	55.0	–	μA

Note:

- The typical value (Typ.) indicates the current value when the CPU and the memory operate. The maximum value (Max.) indicates the current when the CPU, the memory, and the peripheral functions operate and the flash memory is programmed/erased.

REVISION HISTORY

R8C/34W Group, R8C/34X Group, R8C/34Y Group, R8C/34Z Group Datasheet

Rev.	Date	Description	
		Page	Summary
0.10	Apr 09, 2010	—	First Edition issued
1.00	Nov 24, 2010	All	“Preliminary” and “Under development” deleted
		14	Figure 1.5 “Voltage detection circuit” added
		28	Table 4.2 006Ch, 006Dh, 0072h, and 0073h revised
		38 to 43	Tables 4.12 to 4.17 “After Reset” notation revised
		46	Table 5.3 “VI > VSS” → “VI < VSS”, Note 1 revised
		47	Table 5.4 tsAMP revised
		48	Table 5.5 “1,000 times” → “100 times”
		51	Figure 5.3 Note 1 revised
		57	Table 5.15 “Vcc = 5.0 V” added
		61	Table 5.20 revised
		62	Table 5.22 “Vcc = 3.0 V” added, “[2.7 V ≤ Vcc ≤ 4.2 V]” → “[2.7 V ≤ Vcc < 4.2 V]”
		63, 64	Tables 5.23 and 5.24 “[2.7 V ≤ Vcc ≤ 3.3 V]” → “[2.7 V ≤ Vcc < 3.3 V]”
		65	Table 5.27 revised
1.10	Jan 31, 2013	15	Figure 1.6 revised

All trademarks and registered trademarks are the property of their respective owners.

Notice

1. Descriptions of circuits, software and other related information in this document are provided only to illustrate the operation of semiconductor products and application examples. You are fully responsible for the incorporation of these circuits, software, and information in the design of your equipment. Renesas Electronics assumes no responsibility for any losses incurred by you or third parties arising from the use of these circuits, software, or information.
 2. Renesas Electronics has used reasonable care in preparing the information included in this document, but Renesas Electronics does not warrant that such information is error free. Renesas Electronics assumes no liability whatsoever for any damages incurred by you resulting from errors in or omissions from the information included herein.
 3. Renesas Electronics does not assume any liability for infringement of patents, copyrights, or other intellectual property rights of third parties by or arising from the use of Renesas Electronics products or technical information described in this document. No license, express, implied or otherwise, is granted hereby under any patents, copyrights or other intellectual property rights of Renesas Electronics or others.
 4. You should not alter, modify, copy, or otherwise misappropriate any Renesas Electronics product, whether in whole or in part. Renesas Electronics assumes no responsibility for any losses incurred by you or third parties arising from such alteration, modification, copy or otherwise misappropriation of Renesas Electronics product.
 5. Renesas Electronics products are classified according to the following two quality grades: "Standard" and "High Quality". The recommended applications for each Renesas Electronics product depends on the product's quality grade, as indicated below.
"Standard": Computers; office equipment; communications equipment; test and measurement equipment; audio and visual equipment; home electronic appliances; machine tools; personal electronic equipment; and industrial robots etc.
"High Quality": Transportation equipment (automobiles, trains, ships, etc.); traffic control systems; anti-disaster systems; anti-crime systems; and safety equipment etc.
Renesas Electronics products are neither intended nor authorized for use in products or systems that may pose a direct threat to human life or bodily injury (artificial life support devices or systems, surgical implantations etc.), or may cause serious property damages (nuclear reactor control systems, military equipment etc.). You must check the quality grade of each Renesas Electronics product before using it in a particular application. You may not use any Renesas Electronics product for any application for which it is not intended. Renesas Electronics shall not be in any way liable for any damages or losses incurred by you or third parties arising from the use of any Renesas Electronics product for which the product is not intended by Renesas Electronics.
 6. You should use the Renesas Electronics products described in this document within the range specified by Renesas Electronics, especially with respect to the maximum rating, operating supply voltage range, movement power voltage range, heat radiation characteristics, installation and other product characteristics. Renesas Electronics shall have no liability for malfunctions or damages arising out of the use of Renesas Electronics products beyond such specified ranges.
 7. Although Renesas Electronics endeavors to improve the quality and reliability of its products, semiconductor products have specific characteristics such as the occurrence of failure at a certain rate and malfunctions under certain use conditions. Further, Renesas Electronics products are not subject to radiation resistance design. Please be sure to implement safety measures to guard them against the possibility of physical injury, and injury or damage caused by fire in the event of the failure of a Renesas Electronics product, such as safety design for hardware and software including but not limited to redundancy, fire control and malfunction prevention, appropriate treatment for aging degradation or any other appropriate measures. Because the evaluation of microcomputer software alone is very difficult, please evaluate the safety of the final products or systems manufactured by you.
 8. Please contact a Renesas Electronics sales office for details as to environmental matters such as the environmental compatibility of each Renesas Electronics product. Please use Renesas Electronics products in compliance with all applicable laws and regulations that regulate the inclusion or use of controlled substances, including without limitation, the EU RoHS Directive. Renesas Electronics assumes no liability for damages or losses occurring as a result of your noncompliance with applicable laws and regulations.
 9. Renesas Electronics products and technology may not be used for or incorporated into any products or systems whose manufacture, use, or sale is prohibited under any applicable domestic or foreign laws or regulations. You should not use Renesas Electronics products or technology described in this document for any purpose relating to military applications or use by the military, including but not limited to the development of weapons of mass destruction. When exporting the Renesas Electronics products or technology described in this document, you should comply with the applicable export control laws and regulations and follow the procedures required by such laws and regulations.
 10. It is the responsibility of the buyer or distributor of Renesas Electronics products, who distributes, disposes of, or otherwise places the product with a third party, to notify such third party in advance of the contents and conditions set forth in this document, Renesas Electronics assumes no responsibility for any losses incurred by you or third parties as a result of unauthorized use of Renesas Electronics products.
 11. This document may not be reproduced or duplicated in any form, in whole or in part, without prior written consent of Renesas Electronics.
 12. Please contact a Renesas Electronics sales office if you have any questions regarding the information contained in this document or Renesas Electronics products, or if you have any other inquiries.
- (Note 1) "Renesas Electronics" as used in this document means Renesas Electronics Corporation and also includes its majority-owned subsidiaries.
- (Note 2) "Renesas Electronics product(s)" means any product developed or manufactured by or for Renesas Electronics.



SALES OFFICES

Renesas Electronics Corporation

<http://www.renesas.com>

Refer to "<http://www.renesas.com/>" for the latest and detailed information.

Renesas Electronics America Inc.
2880 Scott Boulevard Santa Clara, CA 95050-2554, U.S.A.
Tel: +1-408-588-6000, Fax: +1-408-588-6130

Renesas Electronics Canada Limited
1101 Nicholson Road, Newmarket, Ontario L3Y 9C3, Canada
Tel: +1-905-898-5441, Fax: +1-905-898-3220

Renesas Electronics Europe Limited
Dukes Meadow, Millboard Road, Bourne End, Buckinghamshire, SL8 5FH, U.K.
Tel: +44-1628-651-700, Fax: +44-1628-651-804

Renesas Electronics Europe GmbH
Arcadiastrasse 10, 40472 Düsseldorf, Germany
Tel: +49-211-65030, Fax: +49-211-6503-1327

Renesas Electronics (China) Co., Ltd.
7th Floor, Quantum Plaza, No.27 ZhiChunLu Haidian District, Beijing 100083, P.R.China
Tel: +86-10-8235-1155, Fax: +86-10-8235-7679

Renesas Electronics (Shanghai) Co., Ltd.
Unit 204, 205, AZIA Center, No.1233 Lujiazui Ring Rd., Pudong District, Shanghai 200120, China
Tel: +86-21-5877-1818, Fax: +86-21-6887-7858 / -7898

Renesas Electronics Hong Kong Limited
Unit 1601-1613, 16/F., Tower 2, Grand Century Place, 193 Prince Edward Road West, Mongkok, Kowloon, Hong Kong
Tel: +852-2886-9318, Fax: +852 2886-9022/9044

Renesas Electronics Taiwan Co., Ltd.
13F, No. 363, Fu Shing North Road, Taipei, Taiwan
Tel: +886-2-8175-9600, Fax: +886 2-8175-9670

Renesas Electronics Singapore Pte. Ltd.
80 Bendemeer Road, Unit #06-02 Hyflux Innovation Centre Singapore 339949
Tel: +65-6213-0200, Fax: +65-6213-0300

Renesas Electronics Malaysia Sdn.Bhd.
Unit 906, Block B, Menara Amcorp, Amcorp Trade Centre, No. 18, Jln Persiaran Barat, 46050 Petaling Jaya, Selangor Darul Ehsan, Malaysia
Tel: +60-3-7955-3390, Fax: +60-3-7955-9510

Renesas Electronics Korea Co., Ltd.
11F., Samik Laved. or Bldg., 720-2 Yeoksam-Dong, Kangnam-Ku, Seoul 135-080, Korea
Tel: +82-2-558-3737, Fax: +82-2-558-5141